FEATURES AND SPECIFICATIONS

1.00mm (.039") Pitch PCI Express* connector

87715
Vertical, Through Hole

Molex offers the new PCI Express* revision 2 specs connectors in a through hole configuration for high-bandwidth workstation and server applications

PCI Express is a third generation I/O architecture. PCI-SIG* recently revised the PCI Express specifications from version 1.1 to version 2.0. This revision doubles the PCI Express interconnect bit rate from 2.5 GT/s (gigatransfer per second) to 5 GT/s per lane. Unlike the previous version in which the PCI bus was implemented via multi-drop parallel architecture, the PCI Express incorporates a point-to-point signaling using differential pairs. A 16-lane link now could provide approximately 16Gbps of data-transfer. With this increase in signaling speed, the PCI Express now provides better support to high-bandwidth applications. It is also backward compatible with current PCI Express 1.1 version products.

Molex's through hole connector version of the PCI Express version 2.0 specs provides customers design flexibility for a narrower interconnect links. This would improve data-transfer at a lower cost.

All Molex PCI Express connectors are compliant with PCI-SIG* specifications. For more information on these specifications please see www.pcisig.com

**PCI Express, ExpressModule, and PCI-SIG are trademarks of PCI-SIG*

Features	Benefits
• High-temperature thermoplastic housing	• Withstands lead-free processing
• Complies with PCI-SIG industry specifications	• Allows connectors to support all PCI Express module cards available in the market.
• Keying design allows only one mating orientation	• Ensures correct mating of card module to edge card connector
• Hot Plugging	• Allows for insertion and removal of card without system shut down, facilitates connection in cramped spaces

SPECIFICATIONS

Reference Information
Packaging: Tray
UL File No.: TBD
CSA File No.: TBD
Mates With: PCI Express Card
Designed In: mm

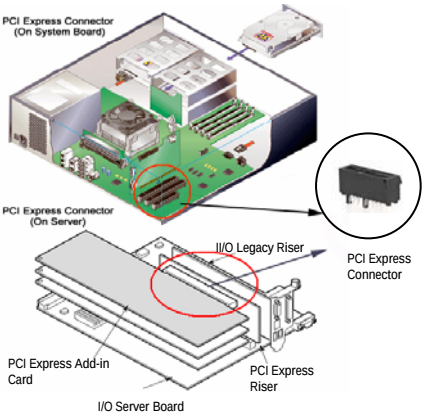
Electrical
Voltage: 50 Volts AC (RMS)/DC
Current: 1.1A
Contact Resistance: 30 milliohms max
Dielectric Withstanding Voltage: 500V AC
Insulation Resistance: 1000 Megohms min

Mechanical
Max Terminal Retention Force: 5 N min/Terminal
Mating Force: 1.15 N max/contact pair
Unmating Force: 0.15 N min/contact pair
Durability: 50 Cycles

Physical
Housing: High Temperature Nylon, UL 94V-0
Contact: Copper Alloy
Plating:
Contact Area — 0.76 µm Gold or 0.38 µm Gold
Solder Tail Area — Tin
Underplating — Nickel
Operating Temperature: - 55 °C to +85 °C

Markets and Applications

- PCI Express 87715
  - Servers
  - Desktop
  - Networking and Communications



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Ordering Information

Descriptions	Order No. (Lead-free)	Plating	PC Tail
PCI Express connector, version 2, Vertical, Through hole Black color	87715-9X00	Gold Flash	2.54mm (0.100")
	87715-9X01	0.254µm (10µ") Gold (Au)	
	87715-9X02	0.38µm (15µ") Gold (Au)	
	87715-9X03	Gold Flash	3.00mm (0.118")
	87715-9X04	0.254µm (10µ") Gold (Au)	
	87715-9X05	0.38µm (15µ") Gold (Au)	
	87715-9X06	0.76µm (30µ") Gold (Au)	2.54mm (0.100")
	87715-9X07	Gold Flash	2.30mm (0.091")
	87715-9X08	0.38µm (15µ") Gold (Au)	
	87715-9X09	0.76µm (30µ") Gold (Au)	3.00mm (0.118")

Circuit size **Replace X with:** 0= 36
1= 64
2 = 98
3= 164

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